

SN8250 CSP Taping Machine

The SN8250 taping machine supports the next-generation CSP package and flip chips. This newly-designed CSP taping machine incorporates processes from pick-up following dicing, inversion handling, image inspection, to sorting and taping.

●Features

- UPH 5,000 (0.7 sec/pc) high-speed processing
- Flexible image processing to suit user requirements
- Easy operation via GUI
- Optional functions can be added to the stage.

●Specifications

- Taping speed UPH 5,000 or more (0.7 sec/pc or less)
- Devices Wafer-level CSPs
Flip chips (0.5 to 3 mm□)
- Wafer sizes Max. 8 inches
- Dicing frame Standard DTF-2-8-1
- Tape sizes Width: 8 mm; Pitch: 2, 4 mm
- Reel sizes Supply reel: Max. φ 600mm
Take-up reel: Max. φ 180mm
Cover tape: Max. φ 200mm



SN9000 μBGA /QFP Taping Machine

The SN9000 is an epoch-making taping machine capable of ultra-high-speed external inspection (Lead 3D) of tray-loaded devices and taping. In standard model, tray-to-taping or tray-to-tray processing can be selected.

●Features

- UPH 8,000 external inspection (tray-to-tray)
- Easy operation via GUI
- Labor-saving, power-saving auto-reject/recovery feature
- Lead inspection using on-the-fly method; device damage during inspection eliminated to maximum extent
- Rear inspection unit can be easily installed as option

●Specifications

- Taping speed UPH 7,000 (0.51 sec/pc)
- External inspection speed UPH 8,000 (0.45 sec/pc)
- Devices CSP, BGA, QFP, TSOP (Max. 30 mm□)
- Tray JEDEC tray
- Tape sizes Width: 8 to 44 mm; Pitch: 8 to 36 mm
- Reel sizes Supply reel: Max. φ 670mm
Take-up reel: Max. φ 330mm
Cover tape: Max. φ 200mm

